



DESCRIPTION

P-channel Enhancement Mode Power MOSFET

FEATURES

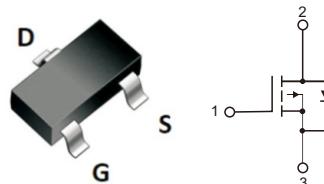
- $V_{DS} = -20V, I_D = -2.5A$
- $R_{DS(ON)} < 120m\Omega @ V_{GS} = -4.5V$
- $R_{DS(ON)} < 160m\Omega @ V_{GS} = -2.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired
- Qualified to ACE-Q101 Standards for High Reliability

APPLICATION

- PWM Applications
- Load Switch
- Power Management

PINNING

PIN	DESCRIPTION
1	GATE
2	DRAIN
3	SOURCE



Simplified outline SOT-23 and symbol



Automotive Grade

Absolute Maximum Ratings (TA=25°C, unless otherwise specified)

Parameter	Symbols	Ratings	Units
Drain-Source Voltage	V_{DSS}	-20	V
Gate-Source Voltage	V_{GSS}	± 12	V
Continuous Drain Current	I_D	-2.5	A
Pulsed Drain Current	I_{DM}	-10	A
Power Dissipation	P_D	1.2	W
Thermal Resistance - Junction to Case (Note3)	$R_{\theta JA}$	104	°C/W
Operation Junction Temperature and Storage Temperature	T_j, T_{stg}	-55 ~ +150	°C



Electrical Characteristics (TA=25°C, unless otherwise specified)

Parameter	Symbols	Text conditions	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	B _{VDSS}	V _{GS} =0V,I _D =-250uA	-20			V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =-20V,V _{GS} =0V			-1	uA
Gate- Source Leakage Current	Forward	V _{GS} =12V,V _{DS} =0V			100	nA
	Reverse	V _{GS} =-12V,V _{DS} =0V			-100	
On Characteristics						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =-250uA	-0.4	-0.7	-1	V
Static Drain-Source On-State Resistance	R _{DSS(ON)}	V _{GS} =-4.5V,I _D =-2.5A		90	120	mΩ
		V _{GS} =-2.5V,I _D =-1.5A		110	160	mΩ
Drain-Source Diode Forward Voltage	V _{SD}	I _S =-2.5A,V _{GS} =0V			-1.2	V
Dynamic Characteristics (Note5)						
Input Capacitance	C _{iss}	V _{DS} =-10V, V _{GS} =0V, f=1.0MHz		285		pF
Output Capacitance	C _{oss}			58		pF
Reverse Transfer Capacitance	C _{rss}			32		pF
Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} =-10V,V _{GS} =-4.5V, I _D =-2.5A (Note1,2)		2.9		nC
Gate-Source Charge	Q _{gs}			0.45		nC
Gate-Drain Charge	Q _{gd}			0.75		nC
Turn-On Delay Time	t _{d(on)}	V _{DD} =-10V,R _{GEN} =3Ω , V _{GS} =-4.5V,R _L =5Ω (Note1,2)		9.8		ns
Turn-On Rise Time	t _r			4.9		ns
Turn-O ffDelay Time	t _{d(off)}			20.5		ns
Turn-O ffFall Time	t _f			7		ns
Turn-O ffDelay Time						
Continuous Current	I _s				-2.5	A
Pulsed Current	I _{SM}				-10	A

Notes:

1. Pulse Test: Pulse width ≤ 300μs, Duty cycle ≤ 2%.
2. Essentially independent of operating temperature typical characteristics.
3. RJA is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins mounted on a 1 inch FR-4 with 2oz.square pad of copper
4. The maximum current rating is package limited
5. Guaranteed by design, not subject to production testing



Typical Performance Characteristics

Figure1: Output Characteristics

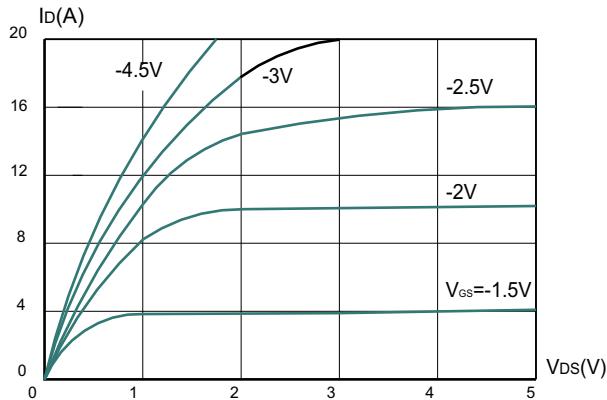


Figure 3: On-resistance vs. Drain Current

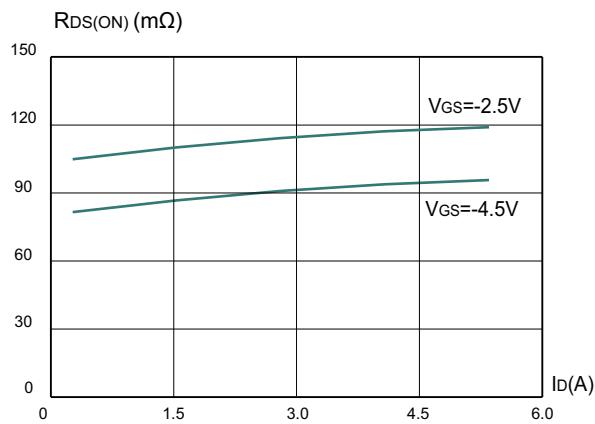


Figure 5: Gate Charge Characteristics

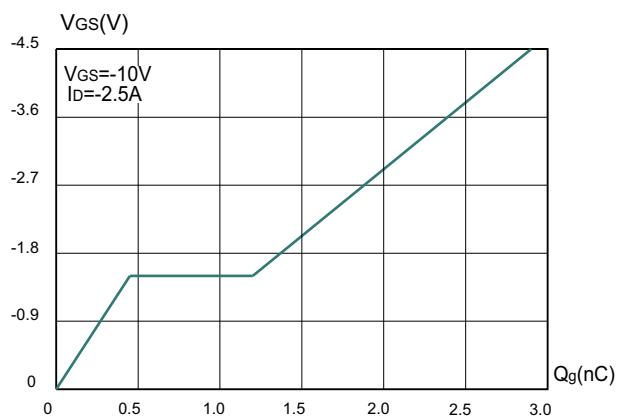


Figure2: Typical Transfer Characteristics

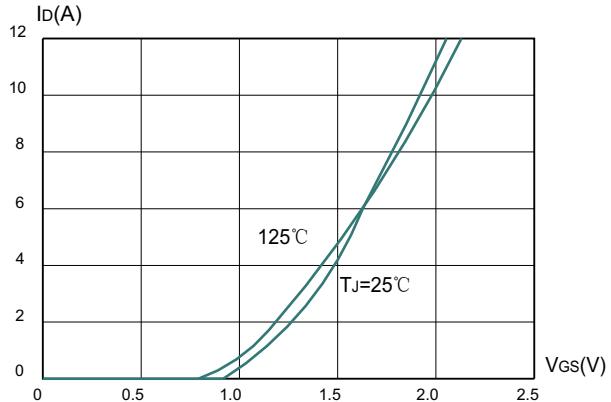


Figure4 : Body Diode Characteristics

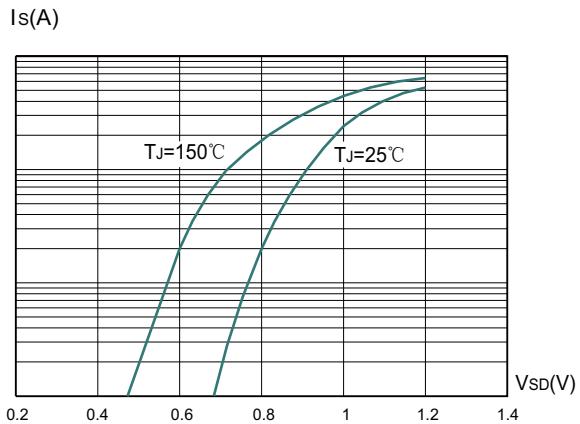


Figure 6: Capacitance Characteristics

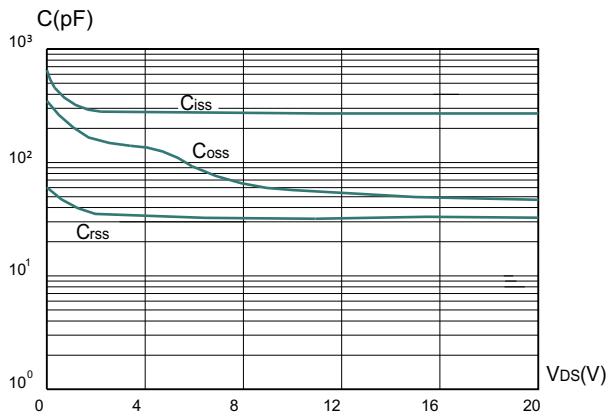




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

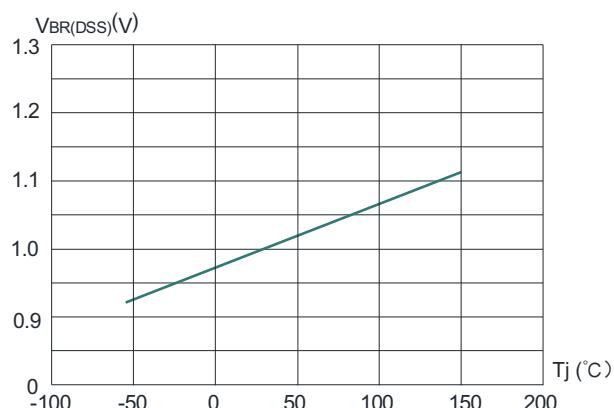


Figure 8: Normalized on Resistance vs. Junction Temperature

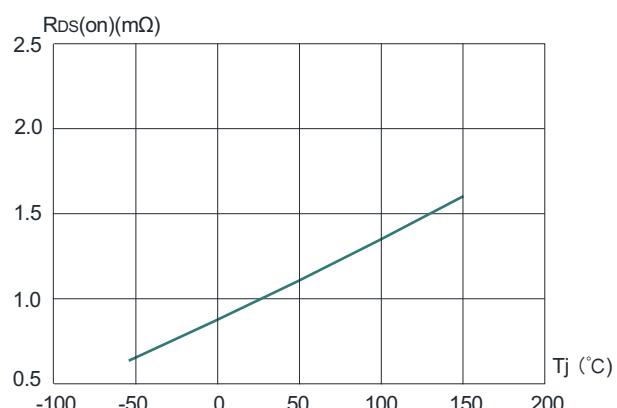


Figure 9: Maximum Safe Operating Area

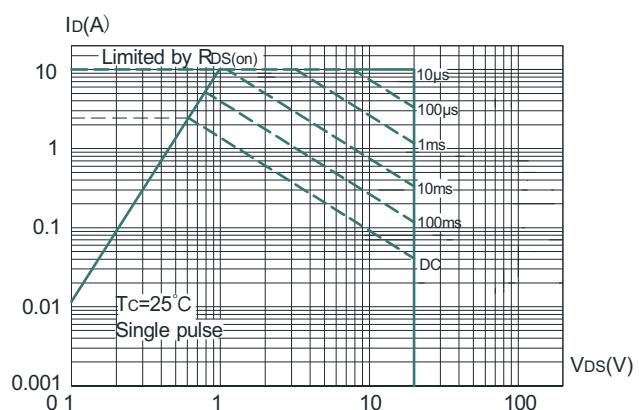


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

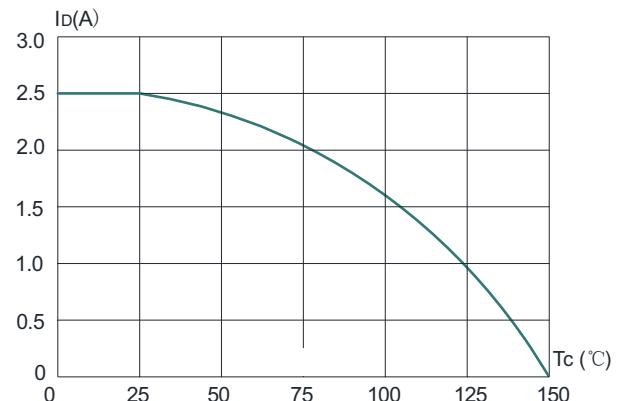
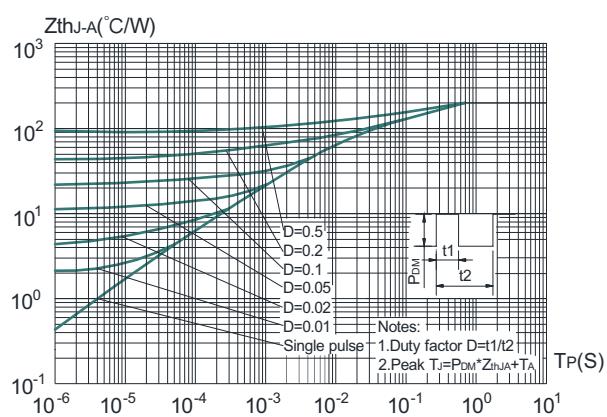
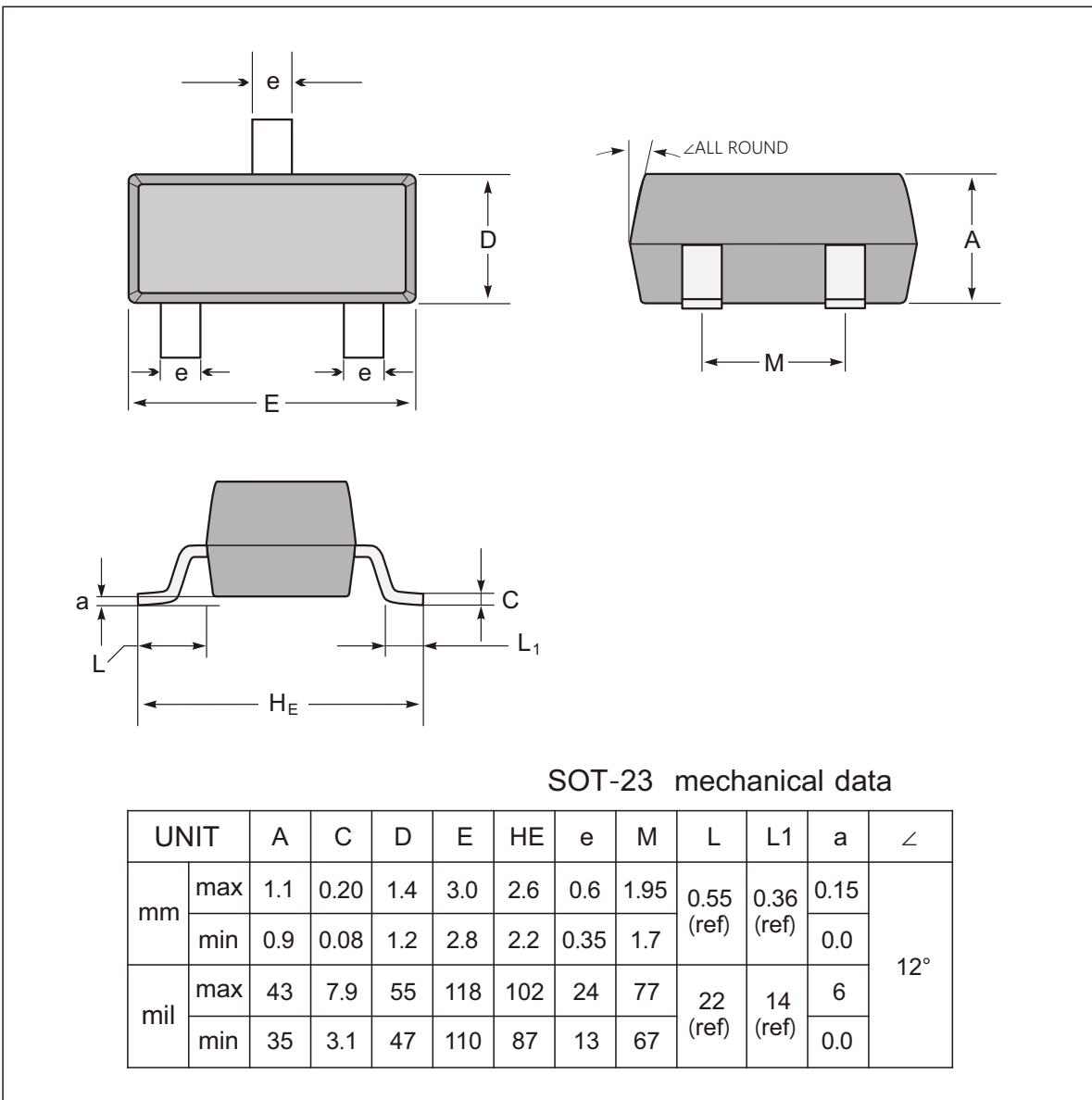


Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

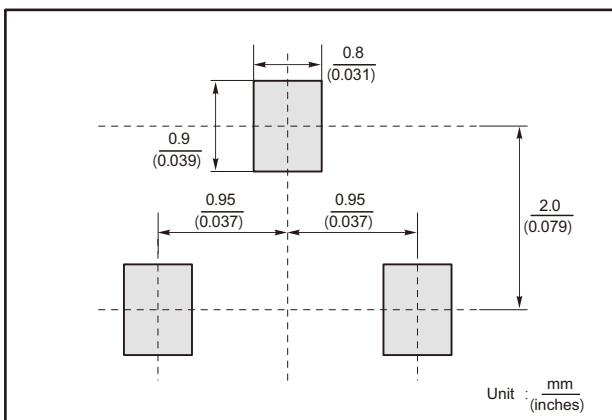




SOT-23 Package Outline Dimensions



The recommended mounting pad size



Marking

Type number	Marking code
PM2301WD	2301



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